IQ-BOND 2476

One component, low CTE underfill adhesive

Pre-Mixed, One Component, Epoxy-based Adhesive

Product Description:

IQ-BOND 2476 is a solvent-free, one-component, pre-mixed, thermoset epoxy based adhesive, developed for underfill applications.

The rheology of IQ-BOND 2476, in combination with its high glass transition temperature and low thermal expansion, make it an ideal solution for high reliability applications in harsh environments.

IQ-BOND 2476 was especially designed to combine high filler loading to minimize the thermal expansion, combined with low viscosity and low thyxotropy. These properties make IQ-BOND 2476 an ideal underfill solution for applications where the thermal expansion (CTE) of the underfill needs to be minimized. To facilitate and accelerate the underfilling process, it can be considered to heat the substrate and/or the IQ-BOND 2476 to about 80°C.

The chemistry of IQ-BOND 2476 has been selected to resist temperatures over 150° C for continuous operation .

The special selected filler type allows a high filler loading, assuring low CTE (coefficient of thermal expansion), which improves thermal cycling performance for applications in harsh environments.

IQ-BOND 2476 can also be used for bonding applications where thin bondlines are required, and will provide good adhesion to materials such as glass, ferrite, aluminum, FR4, ceramic and steel.

As IQ-BOND 2476 is a pre-mixed, one-component epoxy system, it's recommended to store IQ-BOND 2476 at temperatures < -40°C. Frozen storage will also prevent that sedimentation of the filler occurs.

When fully cured, IQ-BOND 2476 is resistant to moisture, cleaning agents and dilute acids and bases. IQ-BOND 2476 is a solvent-free, 100% solids material.

For cleaning un-cured IQ-BOND 2476 from stencils, screens, squeegee, or other equipment, the use of IQ-CLEANER 9500 is recommended.



Product Properties:

- Appearance: White liquid (before cure) → Brown solid (after cure)
- Chemistry: Epoxy
- Odor: Faint
- Mix-Ratio: Not Applicable pre-mixed single component adhesive
- Hegmann Fineness: < 50 μm
- Viscosity at 25°C: ~ 12.500 mPa.s (Brookfield RVII, CP51 at 2 rpm)
- Viscosity at 80°C: ~ 400 mPa.s (Brookfield RVII, CP51 at 20 rpm)



- Filler content (wgt%): ~ 62%
- T_g: ~ 125°C
- CTE₁: ~ 26 ppm
- Shore hardess: ~ 93 shore D
- Service temperature: -55°C to 150°C
- Die shear strength: > 100 kg/cm²
- Density: ~ 1,45 gr/cm³
- Cure Speed:
 - 15 minutes @ 160°C
 - 30 minutes @ 150°C
 - 120 minutes @ 120°C

For good mechanical strength, cure according above conditions is recommended. The final bond strength will depend on the residence time at the given cure temperature. Typically, a higher curing temperature, as well as a longer cure time will result in higher adhesion strength, and improved polymer crosslinking. In any case, it's recommended to consider a post-cure of about 1 hour at temperature similar or above the maximum operation temperature to have optimum properties, and elevated Tg.



Processing parameters:

Prior to use, it's advised to let the adhesive IQ-BOND 2476 equilibrate to room temperature. Depending the size of syringes, 15 – 30 minutes is typically recommended.

Storage stability:

Storage stability is 6 months from date of production, when stored at -40°C, in closed containers.

At room temperature, IQ-BOND 2476 has a worklife / potlife* of ~ 24 hours.

*: Potlife / worklife defined as doubling of initial viscosity

Attention:

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